ABSTRACT

"Plastic cavity package lid seal process"

A method of producing a cavity package semiconductor device is disclosed. The method includes in a package having a body (20) and at least one lid (22) the steps of preparing the lid (22) and body (20); applying adhesive (26) to the lid (22) or the body (20); placing the lid (22) on the body (20); and sealing the lid (22) to the body (20).

This Sheet Has Been Replaced

